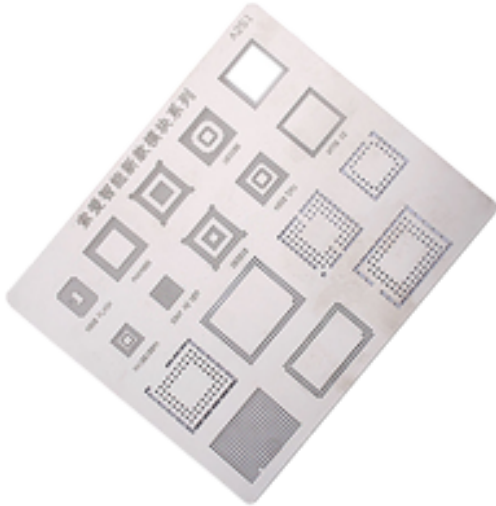


Main page > Repair Equipment > Soldering Equipment > Stencil BGA kit > BGAP for SonyEricsson PDA plaiting kit



## BGAP for SonyEricsson PDA plaiting kit

---

Product ID: 7511

Price: **8.00 EUR**

---

Product weight: **0.02 kg**

### Description:

BGAP for SonyEricsson PDA plaiting kit it's a matrix for that's needed tool when you have to exchange BGA parts of your phone.

#### Contact details:

Telefon: +48 17 227 00 25  
Infolinia: 0 801 671 717  
E-mail: [biuro@multi-com.pl](mailto:biuro@multi-com.pl)  
Skype: Multi-COM

#### Address:

Multi-COM Sp. z o.o.  
ul. Stanisława Krzaklewskiego 31b  
36-100 Kolbuszowa  
POLSKA

[Go to the product](#)

